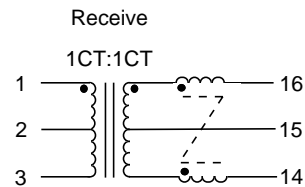
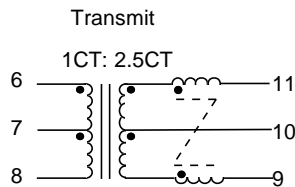


- Robust design allows for toughest soldering processes •
- Complies with or exceeds IEEE 802.3, 10 Base-T Requirements •

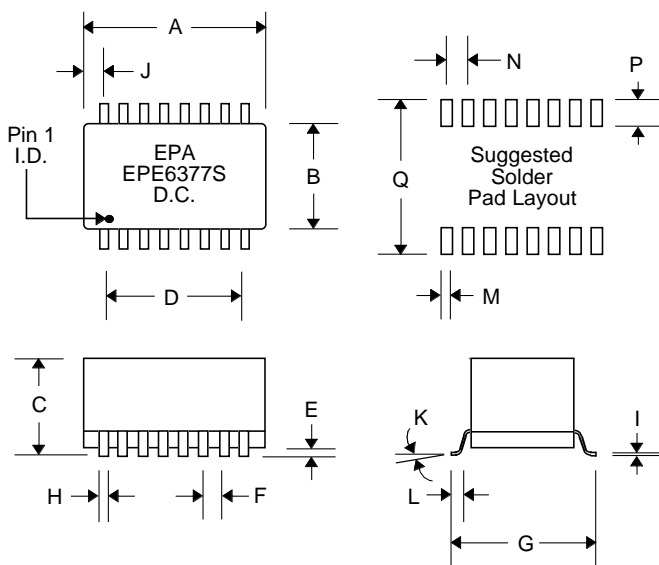
Electrical Parameters @ 25° C

Inductance (μH Min.)		Interwinding Capacitance (pF Max.)		Leakage Inductance (μH Max.)		Hipot (Vrms)	DCR (Ω Max.)	
@ 100 KHz, 20m Vrms		@ 100 KHz, 20m Vrms		@ 100 KHz, 20m Vrms				
Xmit	Rcv	Xmit	Rcv	Xmit	Rcv		Xmit	Rcv
200		15		0.5		2000	0.4	0.4

Schematic



Package



Dimensions

Dim.	(Inches)			(Millimeters)		
	Min.	Max.	Nom.	Min.	Max.	Nom.
A	.440	.460	.450	11.18	11.68	11.43
B	.240	.260	.250	6.10	6.60	6.35
C	.210	.230	.220	5.33	5.84	5.59
D	---	---	.350	---	---	8.89
E	.009	.015	.012	.229	.381	.305
F	---	---	.050	---	---	1.27
G	---	---	.360	---	---	9.14
H	.018	.022	.020	.457	.559	.508
I	.008	.012	.010	.203	.305	.254
J	---	---	.050	---	---	1.27
K	0°	8°	4°	0°	8°	4°
L	.020	.050	.035	.508	1.27	.889
M	---	---	.030	---	---	7.62
N	---	---	.050	---	---	1.27
P	---	---	.055	---	---	1.40
Q	---	---	.380	---	---	9.65